

Electronic Acknowledgement Receipt

EFS ID:	1146916
Application Number:	09712749
Confirmation Number:	9765
Title of Invention:	Low profile integrated module interconnects and method of fabrication
First Named Inventor:	Chia-Yu Fu
Customer Number:	23125
Filer:	David George Dolezal/Dora Hudgins
Filer Authorized By:	David George Dolezal
Attorney Docket Number:	CT00-020
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File Listing:

Document Number	Document Description	File Name	File Size(Bytes)	Multi Part	Pages
1	Request for status of Application	CT00-020-USA-2006-08-09-StatusInquiry.pdf	111274	no	1

Warnings:**Information:****Total Files Size (in bytes):**

111274

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New Applications Under 35 U.S.C. 111

If a new application is being filed and the application includes the necessary components for a filing date (see 37 CFR 1.53(b)-(d) and MPEP 506), a Filing Receipt (37 CFR 1.54) will be issued in due course and the date shown on this Acknowledgement Receipt will establish the filing date of the application.

National Stage of an International Application under 35 U.S.C. 371

If a timely submission to enter the national stage of an international application is compliant with the conditions of 35 U.S.C. 371 and other applicable requirements a Form PCT/DO/EO/903 indicating acceptance of the application as a national stage submission under 35 U.S.C. 371 will be issued in addition to the Filing Receipt, in due course.